

October 19, 2018

PCN

## Relocation of backend production of EPCOS pressure sensor elements

In order to further extend the production capacity, the backend production (dicing, wafer test measurement, optical inspection) of the B58600\* and B58601\* series of EPCOS pressure sensor elements will be relocated in two phases from Stahnsdorf near Berlin to the Beeskowdamm plant in Berlin:

Phase	Scheduled date
1. Release of new Beeskowdamm production plant with duplicate machineries for backend production processes (process release with PPAP to customer).	November 2018 to end of February 2019
2. Relocation of equipment from Stahnsdorf to Beeskowdamm (internal process releases with information note to customer). Closing of backend production in Stahnsdorf.	May 2019

First deliveries from the Beeskowdamm plant are planned starting March 1, 2019 (phase 1).

**Enclosure** PCN (ID No. T122/0205)

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**Customers are asked to address inquiries directly to their sales contacts.**

**TDK Electronics AG**

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**Thermistors, Sensors**  
Internal / External

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## Product / Process Change Notification

<b>1. ID No.:</b> T122/0205		<b>2. Date of announcement:</b> October 19, 2018	
<b>3. Product / product group:</b> EPCOS pressure sensor elements	<b>Old ordering code:</b> B58600*, B58601*	<b>New ordering code:</b> No change	<b>Customer part number:</b>
<b>4. Description of change:</b> Relocation of pressure sensor element backend production (dicing, wafer test measurement, optical inspection) in two phases: Phase 1: Release of new production location Beeskowdamm with duplicate machineries for backend production processes (process release with PPAP to customer). November 2018 to end of February 2019 Phase 2: Relocation of equipment from Stahnsdorf to Beeskowdamm (internal process releases with information note to customer). Closing of backend production in Stahnsdorf. May 2019			
<b>5. Effect on the product or for the customer (benefit, quality, specification, lead time):</b> Capacity extension established for production ramp-up. Depending on approval process there will be no or limited effect on lead time as this is conducted in two phases, doubling of existing equipment at new location additional to running production.			
<b>6. Quality assurance measures / risk assessment:</b> 1. Machine capability studies and process releases acc. to EPCOS Corporate Guide Lines and IATF 16949 (pressure sensing element backend processes). 2. Process studies and equipment release (pressure sensing element backend processes). 3. Product validation in a pressure transducer housing (pressure sensing element). 4. Outgoing test, i.e. AOI and outgoing inspection (for pressure sensing element).			
<b>7. Scheduled date of change:</b> Phase 1: Internal release finished by End of February 2019 Phase 2: Relocation of equipment in May 2019			
<b>8. Estimated date of first delivery of changed product:</b> Possible from March 2019 (Phase 1) If TDK Electronics AG does not receive notification to the contrary within a period of 10 weeks, TDK Electronics AG assumes that the customer agrees to the change. For an interim period we cannot rule out that old as well as new products will be shipped.			
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<b>Customer feedback</b>	
Customer acknowledgement	Signature